EIE

EIE Enterprise (M) Sdn. Bhd. (944691-T)

HI-GRADE #3324 SOLDERING FLUX

Description

Hi-Grade #3324, a completely organic flux containing non-evaporating vehicles, is suitable for all conventional tin-lead alloys, as well as low temperature alloys. It incorporates a unique fluxing ingredient and offers an exceptionally high degree of activity in the soldering and tinning temperatures.

Uses

Hi-Grade #3324 Soldering Flux was developed specifically for tinning copper wires. It has many other uses, such as, armature soldering, printed circuits plated with tin-nickel, tin or tin-nickel-plated plugs and others. In soldering applications where inorganic fluxes are TOO CORROSIVE and rosin fluxes TOO INACTIVE. This flux is ideally suited. If used on other electronic assemblies, every attempt should be made to remove flux residue.

Hi-Grade #3324 is suitable for soldering to additional base metals listed follows:

Silver
Solder (plate)
Lead
Copper
Brass
Gold
Tin-nickel (plate)
Tin (plate)
Cadmium
Bronze
Nickel

Application

Hi-Grade #3324 Soldering Flux is especially adaptable to foam application. However, it can also be applied by brushing, dipping and spraying.

Residue Removal

Flux residues are completely soluble in water, some alcohol and other solvents and are easily removed after soldering.

Physical Properties

Physical state : Clear- Liquid
Specific Gravity : 1.01
Flash Point : None

Precautions

Hi-Grade #3324 is an organic type flux and normal acid handling precautions should be observed in its use. The flux and flux volatile are corrosive and are to be used only with adequate ventilation.

Packing

25 liters or 6 us gallons per container
209 liters or 55 us gallon container

Safety and Precautions

Hi Grade #3324 is an organic type and normal acid handling precautions should be observed in its use. The flux and flux volatiles are corrosive and are to be used only with adequate ventilation.